

Part Number

Customer

Category	Parameter	Specification	Measurement Method	
OverallWafer	1.0	Diameter	100.00 +/- 0.30 mm	WaferVendor
	2.0	Primary Flat Orientation	<110> +/- 1 degree	Wafer Vendor
	3.0	Primary Flat Length	32.50 +/- 2.50 mm	Wafer Vendor
	4.0	Secondary Flat Orientation	none	Wafer Vendor
	5.0	Overall Thickness	391.00 +/- 5.00 um	Guaranteed by Process
	6.0	Total Thickness Variation (TTV)	<3.00um	Guaranteed by Process
	7.0	Bow	<60.00um	Guaranteed by Process
	8.0	Warp	<60.00um	Guaranteed by Process
	9.0	Edge Exclusion	5 mm	Guaranteed by Process
HandleSilicon	10.0	Handle Growth Method	CZ	Wafer Vendor
	11.0	Handle Orientation	<100> +/- 1 degree	Wafer Vendor
	12.0	Handle Thickness	330.00 +/- 5.00 um	Guaranteed by Process. See Notes 1.
	13.0	Handle Doping Type	N	Wafer Vendor
	14.0	Handle Dopant	Antimony	Wafer Vendor
	15.0	Handle Resistivity	< 0.02 Ohmcm	Wafer Vendor
	16.0	Backside Finish	Lapped and etched with oxide and lasermark	Wafer Vendor. See Notes 2.
BuriedOxide	16.1	Oxide Type	Thermal	Guaranteed by Process
	16.2	Oxide Thickness	10,000.00 +/- 500.00 A	Nanospec 45, 5pt
	16.3	Oxide Thickness Device	8,000.00 +/- 400.00 A	nanospec 4%, pt measurement
	16.3	Oxide Thickness Handle	2,000.00 +/- 100.00 A	nanospec 4%, 5pt measurement
DeviceSilicon	17.0	Device Growth Method	CZ	Wafer Vendor
	18.0	Device Orientation	<100> +/- 1 degree	Wafer Vendor
	19.0	Nominal Thickness	60.00 +/- 0.40 um	Guaranteed by Process, FTIR 9pt 100%
	20.0	Distance to device silicon edge from wafer edge	1.5mm +/- 0.5mm	Defined edge
	21.0	Device Doping Type	N	Guaranteed by Process
	22.0	Device Dopant	Antimony	Guaranteed by Process
	23.0	Device Resistivity	< 0.02 Ohmcm	Wafer Vendor
	24.0	Voids	none	Guaranteed by Process, SAM inspection
	25.0	Haze	none	Guaranteed by Process, Bright LIght inspection
26.0	Scratches	none	Guaranteed by Process, Bright LIght inspection	

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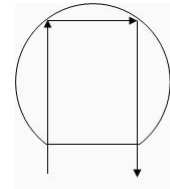
Customer

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DeviceSilicon	27.0	Device Side Scribe	LM001 scribe, duplicate backside scribe - see attached location file	guaranteed by process

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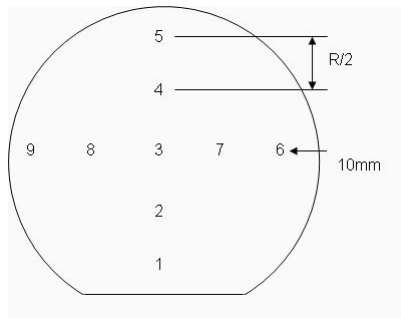
Shipping Details	Wafer per box :	Max 25	
	Packaging :	Taped Polypropylene Wafer Box Empak, Ultrapak, 100.00mm Antistatic Double Bagging	
	Lot Shipment Data	Device Thickness Bow / Warp Data Handle and SOI Thickness	



Explanatory Notes 1. Microscope inspection performed using microscope scan as below. 5x objective.

2. All bright light inspections performed exclude all wafer area outside the edge exclusion defined in Overall Wafer, Edge Exclusion. High intensity bright lamp inspection as per ASTM F523.

3. 9 point measurement are as shown in the diagram below:



Additional Information